

L Number	Hits	Search Text	DB	Time stamp
1	5395	257/666	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 13:37
2	972	257/667	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 13:41
3	815	257/673	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 13:50
4	3289	257/676	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 13:57
5	1115	257/684	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 14:15
6	1200	257/685	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 14:25
7	2789	257/686	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 14:53
8	1218	257/687	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 14:56
9	1733	257/704	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 15:08
10	1473	257/762	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 15:24
11	1886	257/763	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 15:38
12	827	257/766	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 15:54
13	2569	257/777	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 16:02
14	1105	257/782	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 16:19

15	2166	438/108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 16:30
16	1025	438/109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 16:48
17	3808	361/760	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/28 16:51
-	317	257/738	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/09 15:01
-	2488	257/738 and (ball or bump or BGA or array)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 12:24
-	2208	257/738 and (ball or bump or BGA or array or flip)	USPAT	2004/07/08 12:24
-	2510	257/738 and (ball or bump or BGA or array or flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 12:25
-	2488	257/738 and (ball or bump or BGA or array)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 12:25
-	2188	257/738 and (ball or bump or BGA or array)	USPAT	2004/07/08 12:25
-	1954	257/738 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 13:46
-	1954	257/738 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 13:58
-	2670	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 13:51
-	716	257/738 not (257/738 and (ball or bump or BGA or array) and wir\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 13:51
-	1673	257/666 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 14:27
-	323	257/667 and (ball or bump or BGA or array) and wir\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 14:27
-	3167	257/666	USPAT	2004/07/08 15:34
-	1671	257/666 not (257/666 and (ball or bump or BGA or array) and wir\$3)	USPAT	2004/07/08 14:29
-	0	conductive near epoxy with 257/777	USPAT	2004/07/08 14:31

-	34	electrically near conductive near epoxy and 257/777	USPAT	2004/07/08 14:35
-	39	electrically near conductive near epoxy and (438/108 or 438/109)	USPAT	2004/07/08 14:34
-	188	conductive near epoxy and 257/777	USPAT	2004/07/08 14:35
-	61	electrically with conductive near epoxy and 257/777	USPAT	2004/07/08 14:38
-	98	electrically with conductive near epoxy and (257/777 or 438/108 or 438/109)	USPAT	2004/07/08 14:40
-	134	electrically with conductive near epoxy and (257/777 or 438/108 or 438/109 or 257/686)	USPAT	2004/07/08 14:50
-	141	electrically with (conductive or "Ag" or silver) near epoxy and (257/777 or 438/108 or 438/109 or 257/686)	USPAT	2004/07/08 14:56
-	0	electrically with (conductive or "Ag" or silver) near epoxy and (257/777 or 438/108 or 438/109 or 257/686)	JPO	2004/07/08 14:54
-	172	electrically with (conductive or "Ag" or silver) near epoxy and (257/777 or 438/108 or 438/109 or 257/686 or 361/760)	USPAT	2004/07/08 15:21
-	320	electrically with (conductive or "Ag" or silver) with epoxy and (257/777 or 438/108 or 438/109 or 257/686 or 361/760)	USPAT	2004/07/08 15:22
-	235	electrically with (conductive or "Ag" or silver) with epoxy and (257/777 or 438/108 or 438/109 or 257/686 or 361/760) and (ball or bump)	USPAT	2004/07/08 15:22
-	685	257/667	USPAT	2004/07/08 15:34
-	945	257/667	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:05
-	778	257/673	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:15
-	3181	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:10
-	2245	257/676	USPAT	2004/07/08 16:11
-	3329	257/773	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:15
-	2717	257/773	USPAT	2004/07/08 16:39
-	2719	257/774	USPAT	2004/07/08 16:55
-	972	257/776	USPAT	2004/07/08 16:55
-	1162	257/776	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:10
-	2518	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:10
-	1783	257/784	USPAT	2004/07/08 17:19
-	861	257/684	USPAT	2004/07/08 17:20
-	1062	257/684	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 17:45

-	2342	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 17:49
-	3932	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 17:49
-	3410	257/778	USPAT	2004/07/08 18:11
-	2231	257/678	USPAT	2004/07/08 18:57
-	902	257/781	USPAT	2004/07/08 18:57
-	1001	257/781	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 18:58
-	227	257/687	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 20:49
-	1177	257/687	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 20:58
-	1684	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 21:08
-	1397	257/762	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 21:35
-	1854	257/763	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 21:52
-	812	257/766	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 22:16
-	10	"5869869" or "6580162" or "6670215"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 22:28
-	3	"6489183"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/08 22:38
-	1	"4769744".PN.	USPAT	2004/07/08 22:33
-	1	"4811081".PN.	USPAT	2004/07/08 22:33
-	1	"4906314".PN.	USPAT	2004/07/08 22:33
-	1	"5001542".PN.	USPAT	2004/07/08 22:33
-	1	"5148265".PN.	USPAT	2004/07/08 22:34
-	1	"5218168".PN.	USPAT	2004/07/08 22:34
-	1	"5391918".PN.	USPAT	2004/07/08 22:34
-	1	"5559055".PN.	USPAT	2004/07/08 22:34
-	1	"5731231".PN.	USPAT	2004/07/08 22:34
-	1	"5858815".PN.	USPAT	2004/07/08 22:35
-	1	"5950070".PN.	USPAT	2004/07/08 22:35
-	52	5,731,231 5,391,918 5,218,168 4,906,314	USPAT	2004/07/08 22:40

-	1331	5,858,815 5,559,055 5,001,542 4, 811,081 5,950,070	USPAT	2004/07/08 22:40
-	5	5,858,815.pn. 5,559,055.pn. 5,001,542.pn. 4,811,081.pn. 5,950,070.pn.	USPAT	2004/07/08 22:41
-	4	5,148,265.pn. 5,258,330.pn. 5,148,266.pn. 5,346,861.pn.	USPAT	2004/07/08 22:43
-	6	"6221691"	USPAT	2004/07/08 22:44
-	15	4,769,744 6,121,688	USPAT	2004/07/08 22:49
-	0	micron near tech\$4 and wafer and tape	USPAT	2004/07/08 22:50
-	0	Micron near Technology near "Inc." and wafer	USPAT	2004/07/08 22:51
-	6264	Micron near Technology and wafer	USPAT	2004/07/08 22:51
-	756	(Micron near Technology and wafer ) and wafer and tape	USPAT	2004/07/08 22:51
-	1357	(Micron near Technology and wafer ) and wafer and (cut\$4 or dicing or scrib\$3)	USPAT	2004/07/08 23:05
-	2816	wafer and (cut\$4 or dicing or scrib\$3) and (ball or bump) and (metal or cupper or "Cu" or "Al") with layer	USPAT	2004/07/08 23:06
-	1899	wafer and (cut\$4 or dicing or scrib\$3) and (ball or bump) and (metal or cupper or "Cu" or "Al") with layer and (via)	USPAT	2004/07/08 23:09
-	11	6,153,448.pn. 6,064,217.pn. 6,344,401.pn. 6,165,885.pn. 5,137,836.pn. 6,566,745.pn. 5,897,337.pn. 6,309,909.pn. 6,326,697.pn. 6,077,757.pn. 5,834,320.pn.	USPAT	2004/07/09 02:11
-	5494	collector near region	USPAT	2004/07/09 04:56
-	106	collector near region with function	USPAT	2004/07/09 04:58
-	72	collector near region with electrical near connection	USPAT	2004/07/09 05:04
-	0	5143865.pn. and collector near region and electrical near connection	USPAT	2004/07/09 05:04
-	0	5143865.pn. and collector near region and electrical	USPAT	2004/07/09 05:05
-	1	5143865.pn. and collector near region and current	USPAT	2004/07/09 06:02
-	2557	257/787	USPAT	2004/07/09 06:02
-	354	257/787 and multi\$4 near (semiconductor or die or chip or IC)	USPAT	2004/07/09 07:22
-	90	257/788 and multi\$4 near (semiconductor or die or chip or IC)	USPAT	2004/07/09 08:53
-	992	257/685	USPAT	2004/07/09 09:48
-	14	"5245216"	USPAT	2004/07/09 09:50
-	2557	257/787	USPAT	2004/07/09 14:10
-	0	"20020005576"	USPAT	2004/07/09 14:10
-	1	"20020005576"	USPAT; US-PGPUB	2004/07/09 14:10
-	1	"5045408".PN.	USPAT	2004/07/09 14:11
-	1	"5200362".PN.	USPAT	2004/07/09 14:11
-	1	"5736789".PN.	USPAT	2004/07/09 14:11
-	1	"5841192".PN.	USPAT	2004/07/09 14:12
-	1	"5976912".PN.	USPAT	2004/07/09 14:12
-	1	"6001671".PN.	USPAT	2004/07/09 14:14
-	0	"20020132442"	USPAT	2004/07/09 15:02
-	1	"20020132442"	USPAT; US-PGPUB	2004/07/09 15:03

-	1	"4962415".PN.	USPAT	2004/07/09 15:13
-	1	"5049977".PN.	USPAT	2004/07/09 15:13
-	1	"4530152".PN.	USPAT	2004/07/09 15:15
-	1	"4635356".PN.	USPAT	2004/07/09 15:15
-	14	"5245216"	USPAT	2004/07/09 15:17
-	76	"5200362"	USPAT	2004/07/09 15:18